L Number	Hits	Search Text	DB	Time stamp
-	9844	((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2003/06/26 18:44
		elastom\$5 resilient\$5) near2 (conduct\$4)).clm.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB .	
-	10015	((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2002/10/01 07:54
	10010	elastom\$5 resilient\$5) near2 (conduct\$45)).clm.	US-PGPUB;	2002, 10,01 07.01
		Clastome resimontes incare (some determine)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7220	((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2002/10/01 07:57
	7329		US-PGPUB;	2002/10/01 07.57
		elastom\$5 resilient\$5) near2 (conduct\$45)).clm.		
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	10011	((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2002/10/01 07:57
		elastom\$5 resilient\$5) near2 (conduct\$5)).clm.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	733	(((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2002/10/01 07:57
		elastom\$5 resilient\$5) near2 (conduct\$5)).clm.) and	US-PGPUB;	
		capacit\$5.clm.	EPO; JPO;	Ì
			DERWENT;	
			IBM_TDB	
_	264	((((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2002/10/01 07:57
	204	elastom\$5 resilient\$5) near2 (conduct\$5)).clm.) and	US-PGPUB;	
			EPO; JPO;	
		capacit\$5.clm.) and electrode.clm.	DERWENT;	
			l l	
	50	////diambassassassassassassassassassassassassass	IBM_TDB	2002/06/26 10:26
-	53	(((((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2003/06/26 18:36
		elastom\$5 resilient\$5) near2 (conduct\$5)).clm.) and	US-PGPUB;	
		capacit\$5.clm.) and electrode.clm.) and (concentration	EPO; JPO;	
		impurity purity)	DERWENT;	
			IBM_TDB	000000000000000000000000000000000000000
-	17	(((((diaphragm membrane elastic\$5 flexible deformable	USPAT;	2003/06/26 18:28
		elastom\$5 resilient\$5) near2 (conduct\$5)).clm.) and	US-PGPUB;	
		capacit\$5.clm.) and electrode.clm.) and (concentration	EPO; JPO;	
		impurity purity).clm.	DERWENT;	
			IBM_TDB	
-	700	(216/2).CCLS.	USPAT;	2003/06/26 18:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	92	((216/2).CCLS.) and impurit\$4	USPAT;	2003/06/26 18:37
		((2.0.2).0.020.7 2.1.0 1.1.1 2.1.10	US-PGPUB;	
			EPO; JPO;	
			DERWENT	
			IBM_TDB	
	4	///246/2\ CCLC \ and impurit@4 near2 concentration\ and		2002/06/26 10:20
-	1	(((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:39
		etch near1 pit	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:39
		etch near1 pit) and diaphragm	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	

		((0.40,0), 0.01,0)	LIODAT	000000000000000
-	23	((216/2).CCLS.) and impurit\$4 near3 concentration	USPAT;	2003/06/26 18:41
[			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	00	(((040/0) 001 0)	IBM_TDB	0000/00/00 40 40
-	20	(((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:48
		etch	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	45	////246/2) CCLC ) and immurit@4 man2 concentration) and	IBM_TDB	2002/06/26 40:22
-	15	((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT; US-PGPUB;	2003/06/26 19:32
		etch) and (diaphragm membrane elastic\$5 flexible deformable elastom\$5 resilient\$5)	EPO; JPO;	
		deloffiable elastoffiab festilefitab)	DERWENT;	
]			IBM_TDB	
_	3	((((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 19:26
	J	etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	2000/00/20 10.20
		deformable elastom\$5 resilient\$5)) and etch near3 (pit hole	EPO; JPO;	
		groove dip)	DERWENT:	
		910010 4147	IBM_TDB	
_	3	(((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:49
	J	etch near3 (pit hole groove dip)	US-PGPUB;	
		(France 2, 22, 2 4, F)	EPO; JPO;	
	•		DERWENT:	
			IBM_TDB	
-	2	(((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:57
	_	etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	
		deformable elastom\$5 resilient\$5)) and electrode near3	EPO; JPO;	
		dielectric near3 (film layer support substrate cover\$4)	DERWENT;	
		• • • • • • • • • • • • • • • • • • • •	IBM_TDB	
-	1	((((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:55
		etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	
		deformable elastom\$5 resilient\$5)) and electrode near3	EPO; JPO;	
		dielectric near3 (film layer support substrate cover\$4)) and	DERWENT;	
		pressure	IBM_TDB	
-	1	(((((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 18:55
		etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	·-
		deformable elastom\$5 resilient\$5)) and electrode near3	EPO; JPO;	
		dielectric near3 (film layer support substrate cover\$4)) and	DERWENT;	
		pressure) and silicon	IBM_TDB	0000/00/00 40:04
-	11		USPAT;	2003/06/26 19:04
		etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	
		deformable elastom\$5 resilient\$5)) and pressure	EPO; JPO;   DERWENT;	
			IBM TDB	
_	6	((((((216/2).CCLS.) and impurit\$4 near3 concentration) and	USPAT;	2003/06/26 19:27
-	0	etch) and (diaphragm membrane elastic\$5 flexible	US-PGPUB;	2500,00,20 10.21
		deformable elastom\$5 resilient\$5)) and pressure near3	EPO; JPO;	
		(sens\$4 measur\$3 detect test transducer gauge monitor	DERWENT;	
		evaluate estimat\$4 identif\$4 indicat\$4)	IBM_TDB	
-	44167	impurit\$4 near3 concentration	USPAT;	2003/06/26 19:27
	• •	•	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1092	(impurit\$4 near3 concentration) and pressure near3 (sens\$4	USPAT;	2003/06/26 19:29
		measur\$3 detect test transducer gauge monitor evaluate	US-PGPUB;	
		estimat\$4 identif\$4 indicat\$4)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	((impurit\$4 near3 concentration) and pressure near3 (sens\$4	USPAT;	2003/06/26 19:30
		measur\$3 detect test transducer gauge monitor evaluate	US-PGPUB;	
		estimat\$4 identif\$4 indicat\$4)) and etch near3 (pit groove	EPO; JPO;	
		hole dip)	DERWENT;	
		8:43:08 AM Page 2	IBM_TDB	<u> </u>

-	13	(((impurit\$4 near3 concentration) and pressure near3	USPAT;	2003/06/26 19:32
		(sens\$4 measur\$3 detect test transducer gauge monitor	US-PGPUB;	
		evaluate estimat\$4 identif\$4 indicat\$4)) and etch near3 (pit	EPO; JPO;	
		groove hole dip)) and (diaphragm membrane elastic\$5	DERWENT;	
		flexible deformable elastom\$5 resilient\$5)	IBM_TDB	